



K-8301

1 MIL POLYIMIDE/SILICONE FILM TAPE

APPLICATIONS

Designed for very high temperature masking of the gold fingers on printed circuit boards during the wave solder process. Excellent for use as electrical insulation for transformer, motor, coil and capacitor applications in the electronics industry.

Ideal as a **Sublimation Heat Tape** to hold transfer sheets in place while sublimating onto a wide variety of items for the promotional and personalized gifts markets.

Suitable as a **3D Printer Tape** for enhancing filament adhesion on the printer bed during the printing process without leaving any residue upon removal.

FEATURES/BENEFITS

- The high-performance silicone adhesive system features excellent adhesion to printed circuit boards during the wave soldering process with clean, one piece removal.
- The high temperature polyimide film/silicone adhesive combination absorbs heat without shrinking or losing its construction integrity.
- Thin and conformable, with outstanding puncture, tear and abrasion resistance at elevated temperatures.
- Also available on a film release liner and in custom die-cut form for spot masking or sheets.

TECHNICAL DATA

Backing Material	: 1 mil HN Polyimide Film
Adhesive	: Silicone
Tape Thickness	: 2.5 mil (0.056mm)
Color	: Amber
Elongation	: 55%
Adhesion to Steel	: 25 oz per inch of width (2.80N/cm)
Tensile Strength	: 30 lbs per inch of width (44 N/cm)
Dielectric Strength	: 6,500 Volts
Insulation Class	: 180°C (UL Recognized Class H)
Temperature Range	: -100°F to 500°F (-73° to 260°C)
Specifications	: MIL-P-46112B, UL 510 Flame Retardant
	: ASTM D-5213, Type 1, Item A
	: RoHs/REACH Compliant

Note: The above are typical values obtained from tests recommended by the PSTC, ASTM, or government agencies and should not be used in writing specifications. The product should be thoroughly evaluated by the user under actual conditions with intended substrates to determine if the product is suitable for the application.